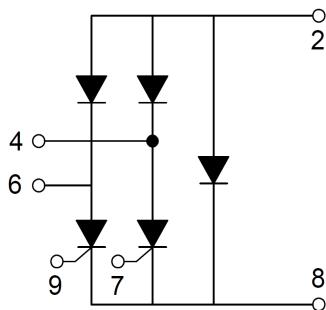


PRODUCT FEATURES

- Electrically Isolated by DBC Ceramic
- High Surge Current Capability
- Low Inductance Package

APPLICATIONS

- DC Motor Control and Drives
- Supply for DC power Equipment



MAXIMUM VOLTAGE RATINGS

 $T_c = 25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter/Test Conditions	Values		Unit
		MMK35LB160HB		
V_{RRM}	Repetitive Peak Reverse Voltage	1600		V
V_{DRM}	Repetitive Peak Off State Voltage			
V_{RSM}	Non-Repetitive Peak Reverse Voltage			

ABSOLUTE MAXIMUM RATINGS (Thyristor)

Symbol	Parameter/Test Conditions	Values	Unit
$I_{T(AV)}$	Average On State Current	35	A
$I_{T(RMS)}$	R.M.S. On State Current		
I_{TSM}	Non-Repetitive Surge On-State Current	450/500	
I^2t	For Fusing	1012/1037	A^2s
T_J	Junction Temperature(Thyristor)	-40 to +125	$^\circ\text{C}$

ABSOLUTE MAXIMUM RATINGS (Diode)

Symbol	Parameter/Test Conditions	Values	Unit
$I_{F(AV)}$	Average Forward Current	35	A
$I_{F(RMS)}$	R.M.S. Forward Current		
I_{FSM}	Non-Repetitive Surge Forward Current	600/650	
I^2t	For Fusing	1800/1753	A^2s
T_J	Junction Temperature(Diode)	-40 to +150	$^\circ\text{C}$

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ELECTRICAL CHARACTERISTICS (Thyristor) $T_C = 25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter/Test Conditions	Min.	Typ.	Max.	Unit	
I_{DRM}	Maximum Peak Off-State Current $V_D = V_{DRM}, T_J = 125^\circ\text{C}$			25	mA	
I_{RRM}	Maximum Peak Reverse Current $V_R = V_{RRM}, T_J = 125^\circ\text{C}$			25		
V_{TM}	Maximum on-state voltage drop $I_{TM}=110\text{A}, t_d=10\text{ ms, half sine}$			1.75	V	
V_{TO}	For power-loss calculations only	$T_J = 125^\circ\text{C}$		0.97	V	
r_T				8.8	$\text{m}\Omega$	
V_{GT}	Max. required DC gate voltage to trigger	$V_A=6\text{V}, R_A=1\Omega, T_J = -40^\circ\text{C}$		4.0	V	
		$V_A=6\text{V}, R_A=1\Omega$		1.0		
		$V_A=6\text{V}, R_A=1\Omega, T_J = 125^\circ\text{C}$		1.7		
I_{GT}	Max. required DC gate current to trigger	$V_A=6\text{V}, R_A=1\Omega, T_J = -40^\circ\text{C}$		270	mA	
		$V_A=6\text{V}, R_A=1\Omega$		75		
		$V_A=6\text{V}, R_A=1\Omega, T_J = 125^\circ\text{C}$		150		
				80		
V_{GD}	Max. required DC gate voltage not to trigger, $V_D = V_{DRM}, T_J = 125^\circ\text{C}$			0.25	V	
I_{GD}	Max. required DC gate current not to trigger, $V_D = V_{DRM}, T_J = 125^\circ\text{C}$			6	mA	
I_H	Maximum holding current			100	200	mA
I_L	Maximum latching current			200	400	mA
P_{GM}	Maximum peak gate power			10	W	
$P_{G(AV)}$	Maximum average gate power			2.5		
I_{GM}	Maximum peak gate current			2.5	A	
$-V_{GM}$	Maximum peak negative gate voltage			10	V	
dv/dt	Critical Rate of Rise of Off-State Voltage, $T_J=125^\circ\text{C}$, exponential to 67% rated V_{DRM}			1000	$\text{V}/\mu\text{s}$	
di/dt	Max. Rate of Rise of Turned-on Current, $T_J = 125^\circ\text{C}, I_{TM}=110\text{A}$, rated V_{DRM}			150	$\text{A}/\mu\text{s}$	

ELECTRICAL CHARACTERISTICS (Diode)

Symbol	Parameter/Test Conditions	Min.	Typ.	Max.	Unit	
I_{RM}	Maximum Reverse Leakage Current	$V_R = V_{RRM}$		0.5	mA	
		$V_R = V_{RRM}, T_J = 125^\circ\text{C}$		10		
V_F	Forward Voltage Drop	$I_F=35\text{A}$		1.02	1.25	V
V_{TO}	For power-loss calculations only , $T_J = 125^\circ\text{C}$			0.88	V	
r_T				8.5	$\text{m}\Omega$	

MODULE CHARACTERISTICS $T_C = 25^\circ\text{C}$ unless otherwise specified

T_J	Junction Temperature		-40 to +125	°C
T_{STG}	Storage Temperature Range		-40 to +125	°C
V_{ISO}	Isolation Breakdown Voltage	AC, 50Hz(R.M.S), t=1minute	3000	V
Torque	to heatsink	Recommended (M5)	2.5~5	N.m
$R_{th(J-C)}$	Junction-to-Case Thermal Resistance(Per Thyristor/Per Diode)		0.6/1.0	K /W
Weight			85	g

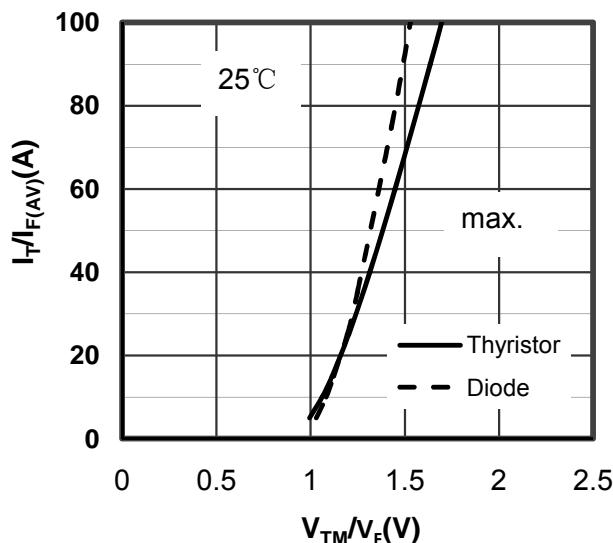


Figure 1. Forward Voltage Drop vs Forward Current

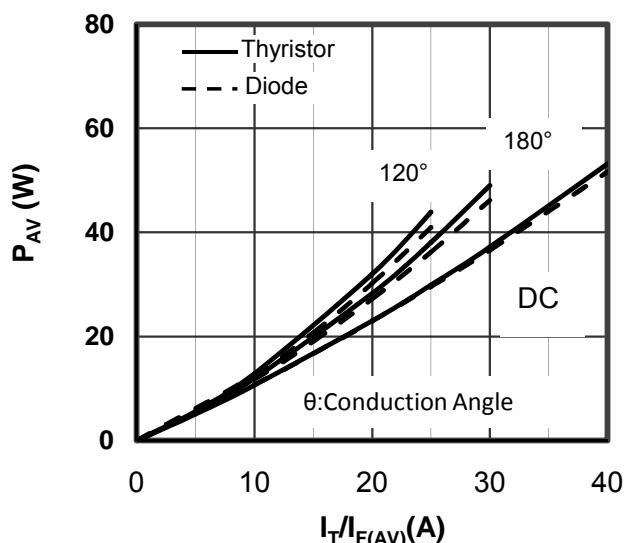
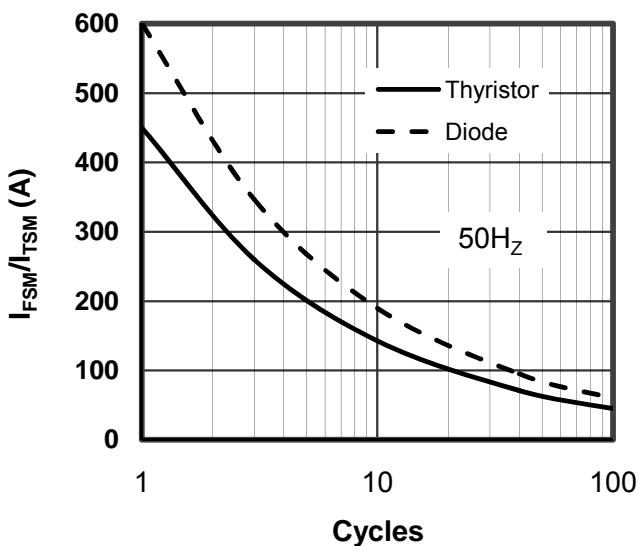
Figure 2. Power dissipation vs. $I_T/I_{F(AV)}$ 

Figure 3. Diode and SCR Max Non-Repetitive Surge

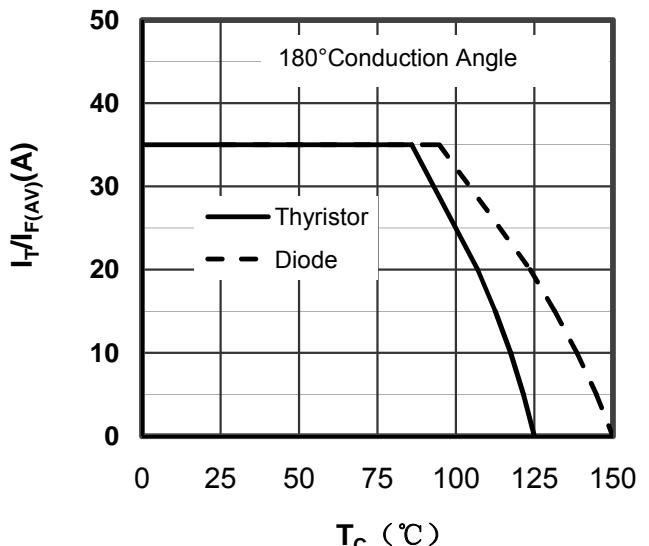
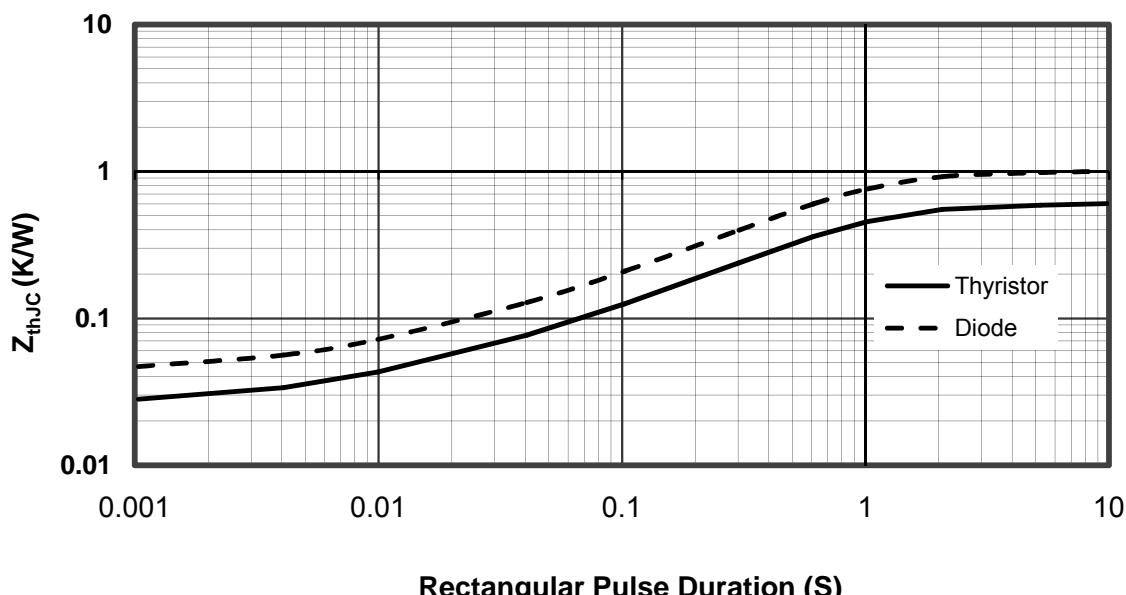
Figure 4. Diode $I_{F(AV)}$ and SCR $I_{T(AV)}$ vs. T_C 

Figure 5. Transient Thermal Impedance of Diode and SCR

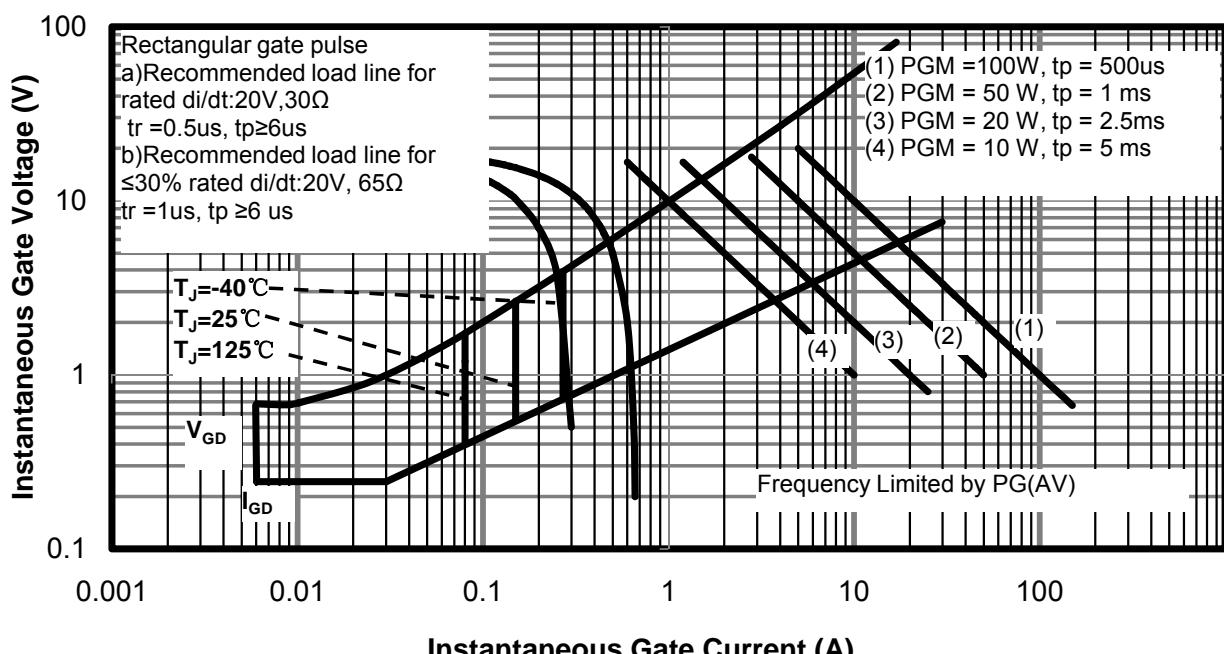
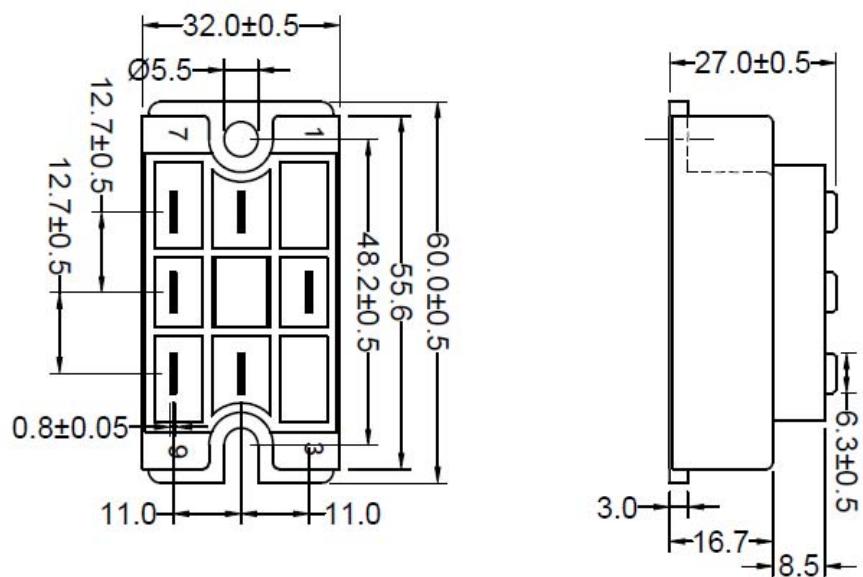


Figure 6. SCR Gate Characteristics



Dimensions in (mm)
Figure 7. Package Outline